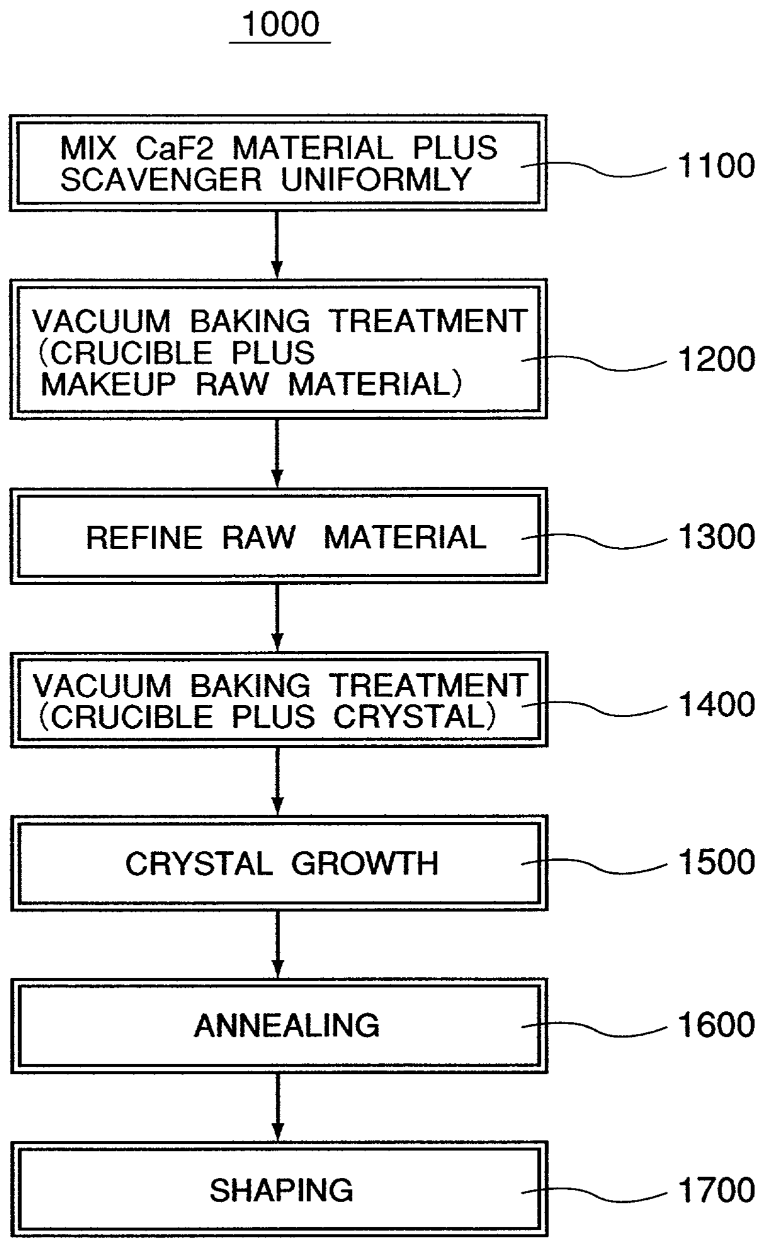
1000
MIX CaF2 MATERIAL PLUS SCAVENGER UNIFORMLY
1100
VACUUM BAKING TREATMENT (CRUCIBLE PLUS MAKEUP RAW MATERIAL)
1200
REFINE RAW MATERIAL
1300
VACUUM BAKING TREATMENT (CRUCIBLE PLUS CRYSTAL)
1400
CRYSTAL GROWTH
1500
ANNEALING
1600
SHAPING
1700

FIG. 1

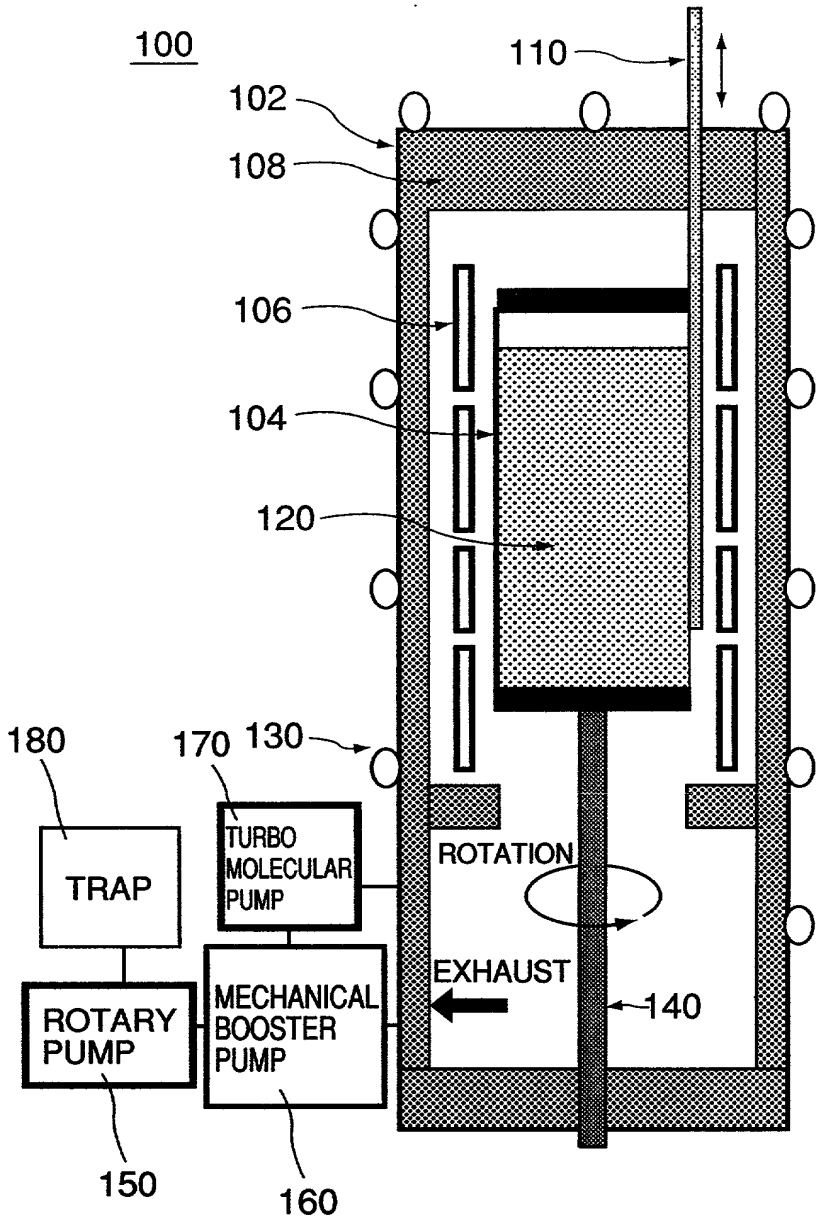
100
110
102
108
106
104
120
130
180
170
TRAP
TURBO MOLECULAR PUMP
ROTATION
EXHAUST
140
ROTARY PUMP
MECHANICAL BOOSTER PUMP
150
160

FIG. 2

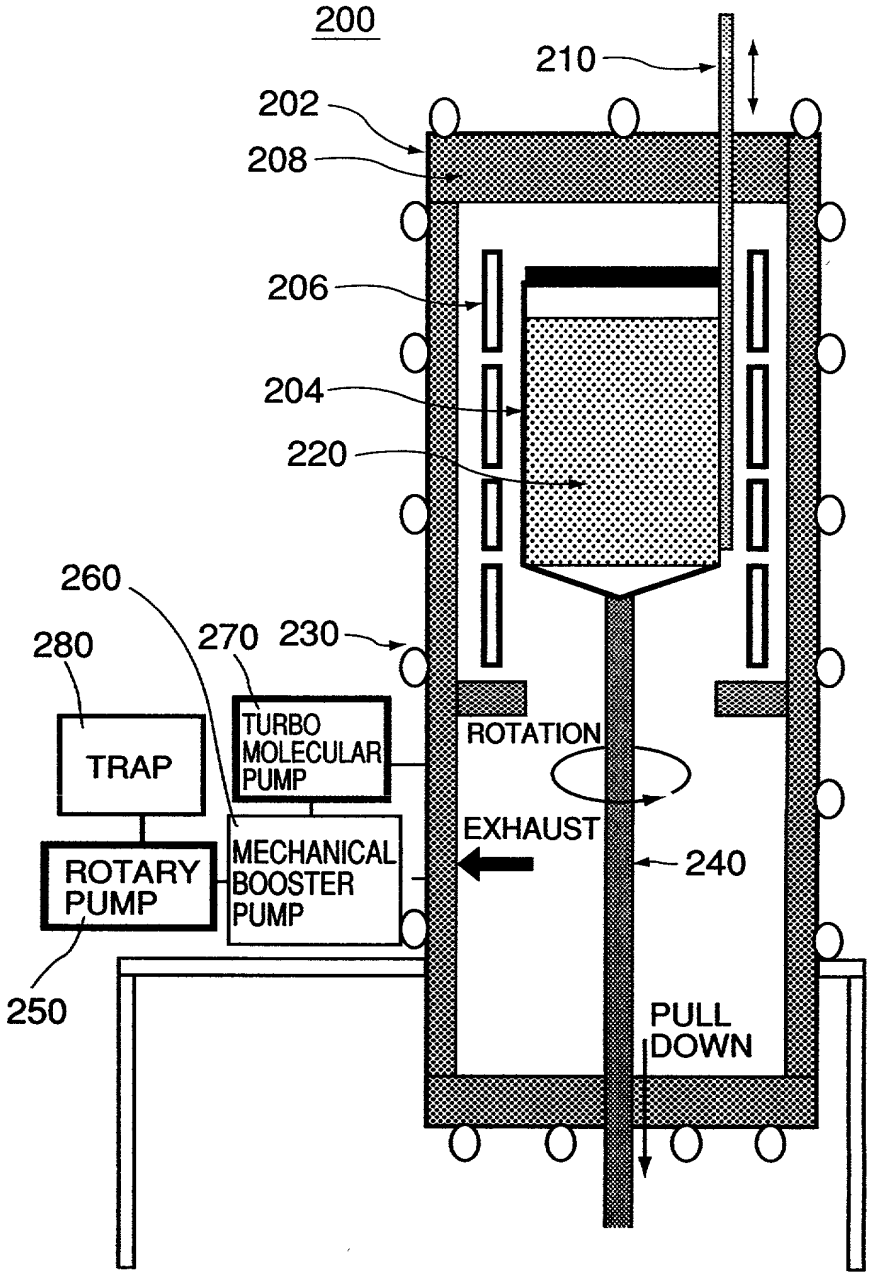
200
210
202
208
206
204
220
260
280
270
230
TRAP
TURBO MOLECULAR PUMP
ROTATION
EXHAUST
240
ROTARY PUMP
MECHANICAL BOOSTER PUMP
250
PULL DOWN

FIG. 3

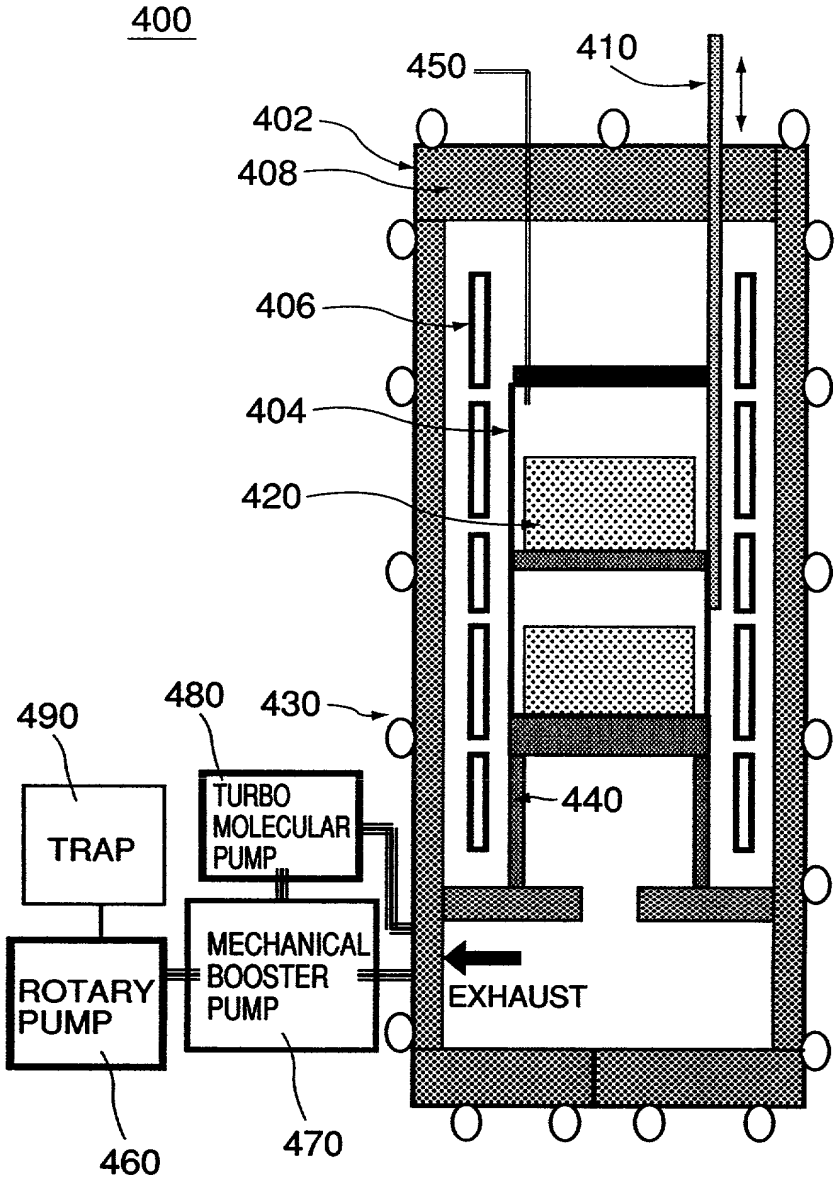
400
450
410
402
408
406
404
420
430
480
490
440
TURBO
MOLECULAR
PUMP
TRAP
MECHANICAL
BOOSTER
PUMP
ROTARY
PUMP
EXHAUST
460
470

FIG. 4

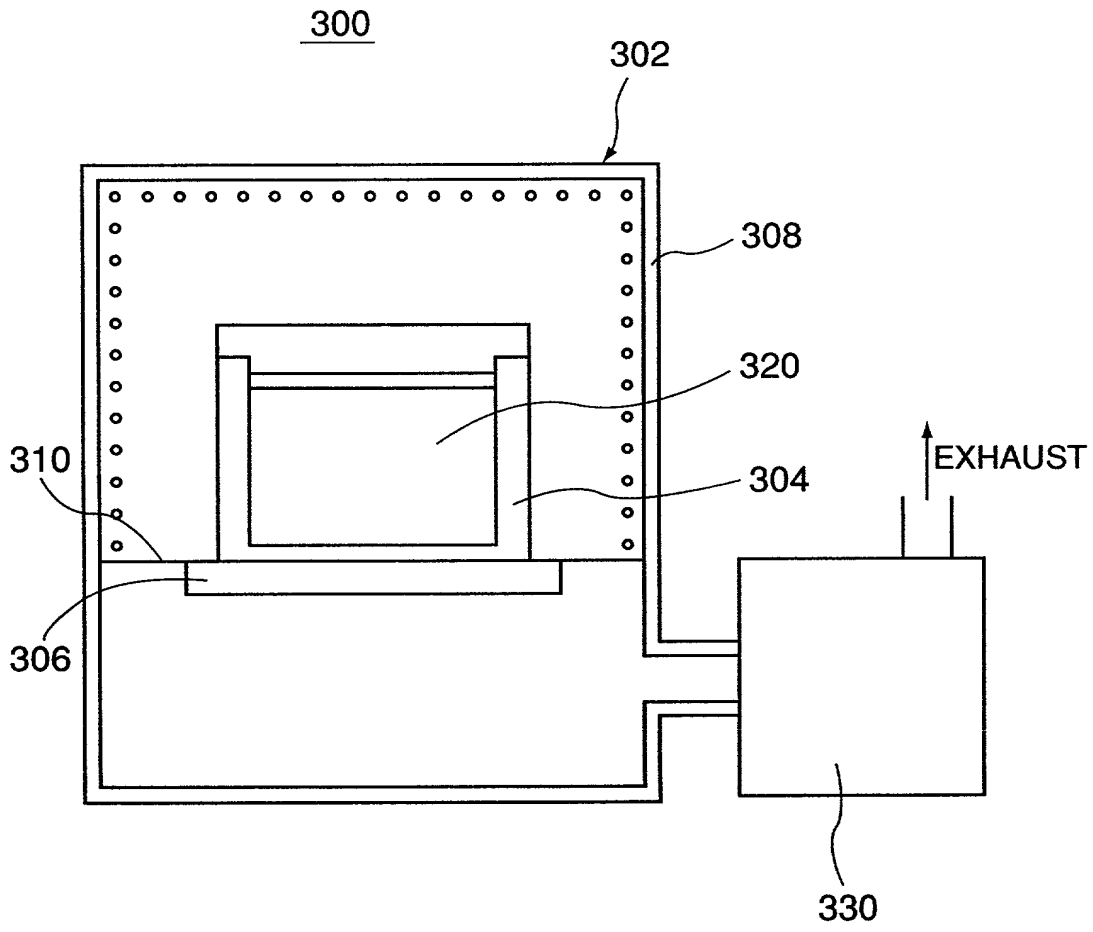

FIG. 5

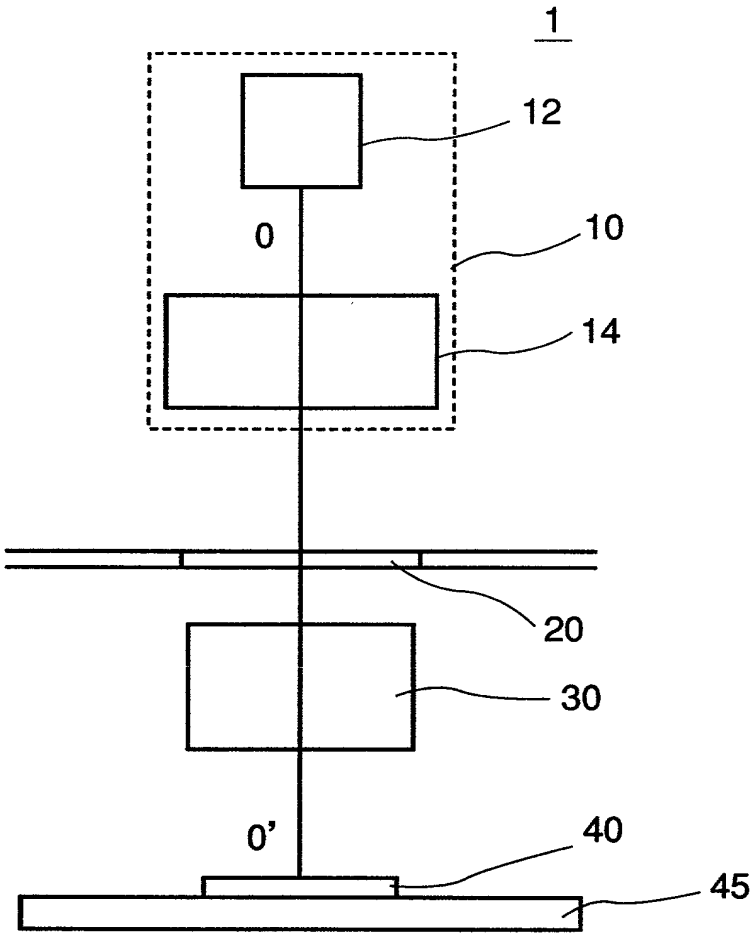

FIG. 6

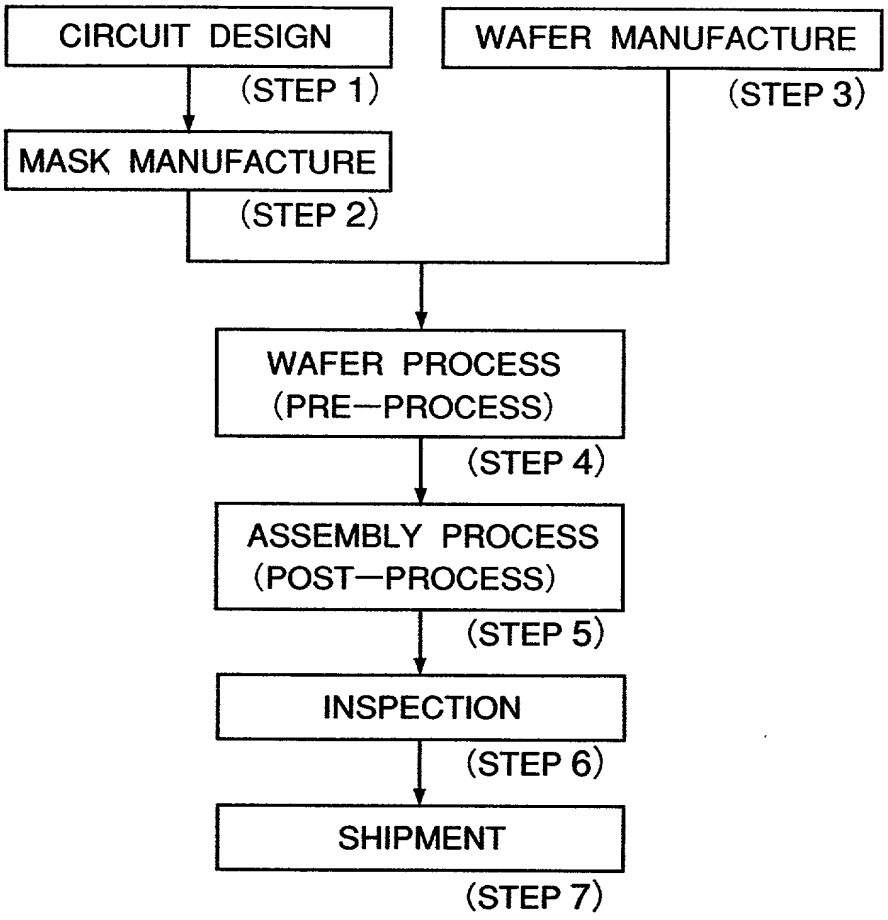
CIRCUIT DESIGN
(STEP 1)
MASK MANUFACTURE
(STEP 2)
WAFER MANUFACTURE
(STEP 3)
WAFER PROCESS
(PRE—PROCESS)
(STEP 4)
ASSEMBLY PROCESS
(POST—PROCESS)
(STEP 5)
INSPECTION
(STEP 6)
SHIPMENT
(STEP 7)

FIG. 7

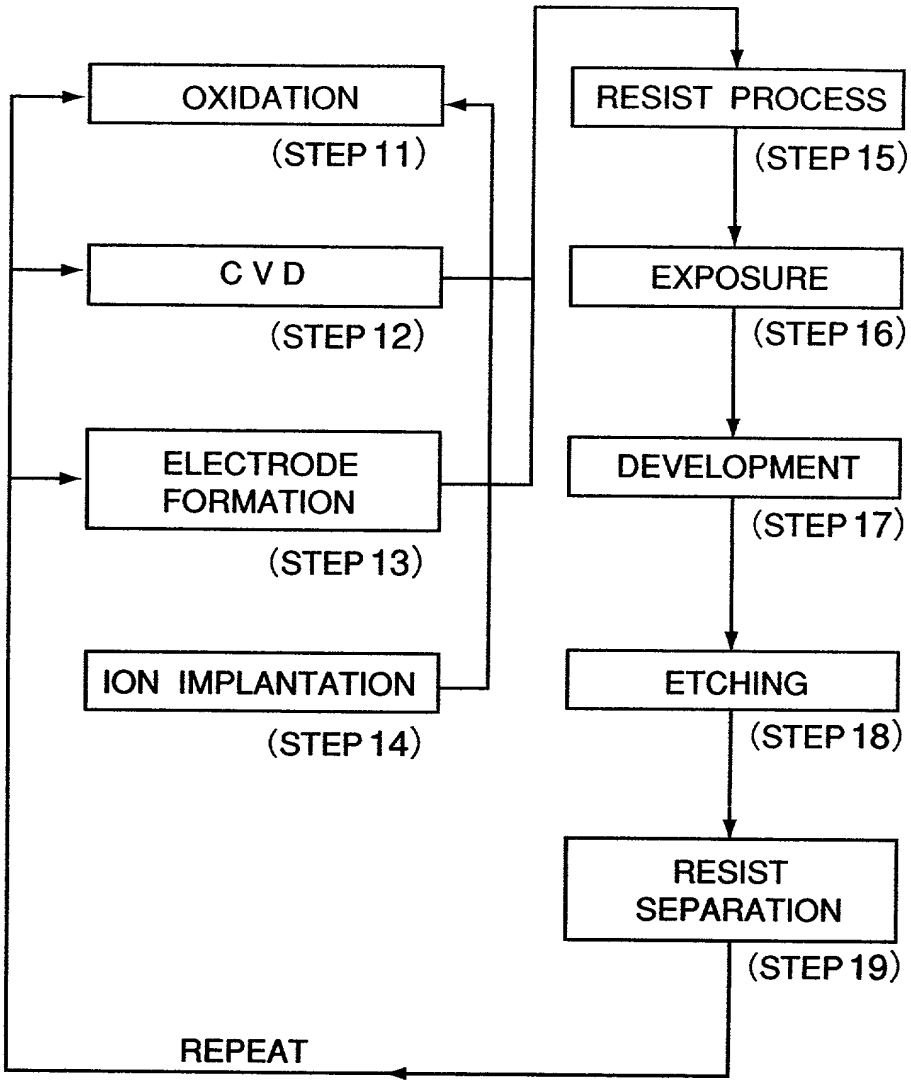
OXIDATION
(STEP 11)
C V D
(STEP 12)
ELECTRODE FORMATION
(STEP 13)
ION IMPLANTATION
(STEP 14)
RESIST PROCESS
(STEP 15)
EXPOSURE
(STEP 16)
DEVELOPMENT
(STEP 17)
ETCHING
(STEP 18)
RESIST SEPARATION
(STEP 19)
REPEAT

FIG. 8